Abstract

Process for cleaning, drying and hydrophilizing a semiconductor wafer

The invention relates to a process for cleaning, drying and hydrophilizing a semiconductor wafer, comprising the following steps in the order stated:
a) treating the semiconductor wafer with a liquid aqueous solution containing hydrogen fluoride, the semiconductor wafer rotating about its centre axis at least occasionally, and
b) drying the semiconductor wafer by rotation of the semiconductor wafer about its centre axis at a rotational speed of 1000 to 5000 revolutions per minute in an ozone-containing atmosphere, the liquid aqueous solution containing hydrogen fluoride flowing away from the semiconductor wafer on account of the centrifugal force generated by the rotation and the surface of the semiconductor wafer being hydrophilized by ozone.

(No figure)